

USB EDC Horizontal 2SE

Customer:

Customer

Part Number:

Innodisk

Part Number:

Innodisk

Model Name:

Date:

Innodisk Approver	Customer Approver

Table of contents

TABLE OF CONTENTS.....	2
REVISION HISTORY	3
LIST OF FIGURES	4
LIST OF TABLES	5
1. PRODUCT OVERVIEW	6
1.1 INTRODUCTION OF USB EDC	6
1.2 PRODUCT VIEW.....	6
1.3 PRODUCT MODELS	6
1.4 CAPACITY.....	6
1.5 VID/PID.....	6
2. THEORY OF OPERATION	7
2.1 OVERVIEW.....	7
2.2 ERROR DETECTION AND CORRECTION	7
2.3 WEAR-LEVELING	7
2.4 BAD BLOCKS MANAGEMENT	8
3. SPECIFICATIONS.....	9
3.1 CE AND FCC COMPATIBILITY	9
3.2 RoHS COMPLIANCE	9
3.3 ENVIRONMENTAL SPECIFICATIONS.....	9
3.4 PIN ASSIGNMENT	10
3.5 MECHANICAL DIMENSIONS	11
3.6 WEIGHT	12
3.7 PERFORMANCE.....	12
3.8 NAND FLASH MEMORY	12
4. ELECTRICAL SPECIFICATIONS	13
4.1 POWER REQUIREMENT.....	13
4.2 POWER CONSUMPTION	13
4.3 DEVICE PARAMETERS	13
5. PART NUMBER RULE	14

REVISION HISTORY

Revision	Description	Date
1.0	First Release	May, 2013
1.1	Modify mechanical drawing Add TBW	Sep, 2013
1.2	Modify TBW based on NAND Flash specifications	Jan, 2015
1.3	Modify mechanical drawing	Apr, 2016
1.4	Modify power requirement Add mechanical tolerance	Jan, 2017
1.5	Update product picture	Feb, 2017
1.6	Update REACH and RoHS certification	Jul., 2017

List of Figures

FIGURE 1: USB EDC HORIZONTAL 2SE6

FIGURE 2: USB EDC HORIZONTAL 2SE BLOCK DIAGRAM.....7

FIGURE 3: USB EDC HORIZONTAL 2SE MECHANICAL DIMENSIONS11

List of Tables

TABLE 1: SHOCK/VIBRATION TESTING FOR USB EDC HORIZONTAL 2SE.....9

TABLE 2: USB EDC HORIZONTAL 2SE MTBF.....10

TABLE 3: USB EDC HORIZONTAL 2SE TBW10

TABLE 4: USB EDC HORIZONTAL 2SE PIN ASSIGNMENT10

TABLE 5: USB EDC HORIZONTAL 2SE POWER REQUIREMENT13

TABLE 6: USB EDC HORIZONTAL 2SE POWER CONSUMPTION13

TABLE 7: USB EDC HORIZONTAL 2SE DEVICE PARAMETERS13

1. Product Overview

1.1 Introduction of USB EDC

The Innodisk USB EDC (Embedded Disk Card) products provide high capacity USB flash memory storage that electrically complies with High-speed USB 2.0 interface & backward compatible with USB 1.1. The device features attractive small form factor and the connectivity over USB2.0 and the NAND flash architecture provide a faster data transmission.

1.2 Product View

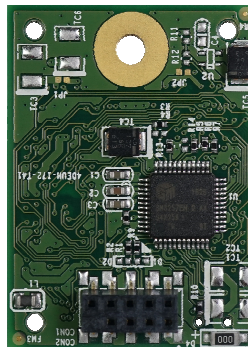


Figure 1: USB EDC Horizontal 2SE

1.3 Product Models

USB EDC Horizontal 2SE is available in follow capacities.

- USB EDC Horizontal 2SE 512MB
- USB EDC Horizontal 2SE 1GB
- USB EDC Horizontal 2SE 2GB
- USB EDC Horizontal 2SE 4GB
- USB EDC Horizontal 2SE 8GB
- USB EDC Horizontal 2SE 16GB
- USB EDC Horizontal 2SE 32GB

1.4 Capacity

USB EDC Horizontal 2SE provides unformatted from 512MB up to 32GB capacities within SLC Flash IC.

1.5 VID/PID

Customize VID/PID(specify 4bits for each ID, Hexadecimal(0~F))

For Option, Default is 196D/0201.

2. Theory of operation

2.1 Overview

Figure 2 shows the operation of USB EDC Horizontal 2SE from the system level, including the major hardware blocks.

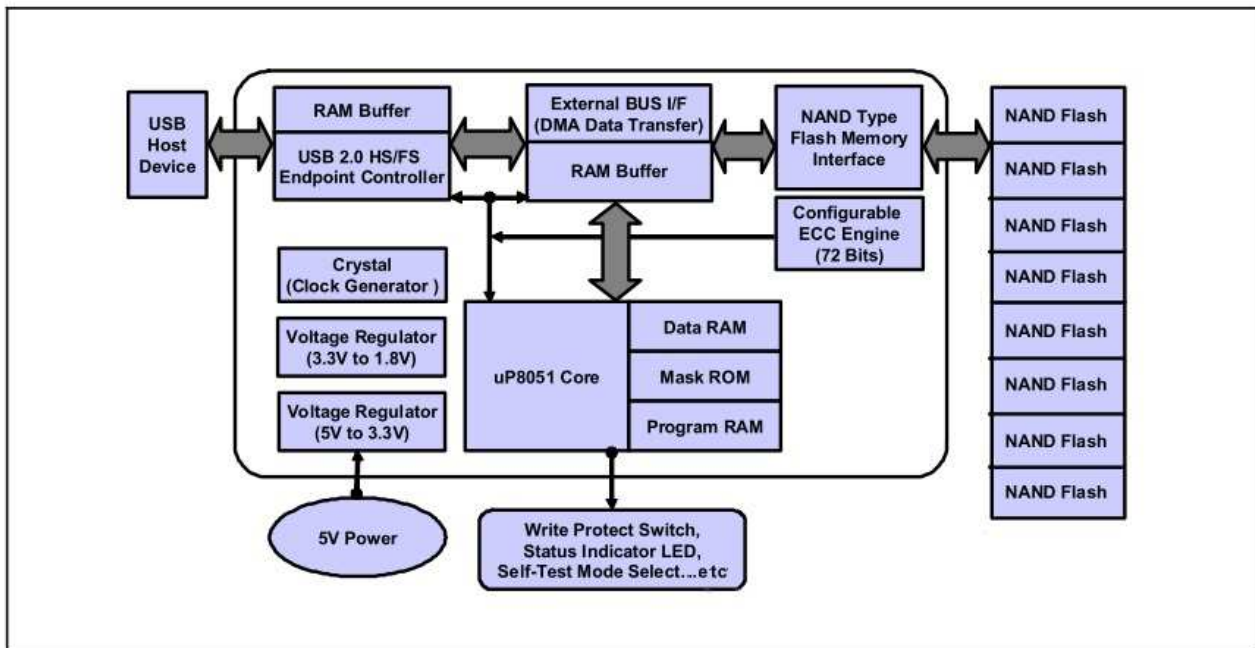


Figure 2: USB EDC Horizontal 2SE Block Diagram

USB EDC Horizontal 2SE integrates a USB2.0 controller and NAND flash memories. Communication with the host occurs through the host interface. Communication with the flash device(s) occurs through the flash interface.

2.2 Error Detection and Correction

Highly sophisticated Error Correction Code algorithms are implemented. The ECC unit consists of the Parity Unit (parity-byte generation) and the Syndrome Unit (syndrome-byte computation). This unit implements an algorithm that can correct 72 bits per 1024 bytes in an ECC block. Code-byte generation during write operations, as well as error detection during read operation, is implemented on the fly without any speed penalties.

2.3 Wear-Leveling

Flash memory can be erased within a limited number of times. This number is called the *erase cycle limit* or *write endurance limit* and is defined by the flash array vendor. The erase cycle limit applies to each individual erase block in the flash device.

USB EDC Horizontal 2SE uses a static wear-leveling algorithm to ensure that consecutive writes of a specific

sector are not written physically to the same page/block in the flash. This spreads flash media usage evenly across all pages, thereby extending flash lifetime.

2.4 Bad Blocks Management

Bad Blocks are blocks that contain one or more invalid bits whose reliability are not guaranteed. The Bad Blocks may be presented while the SSD is shipped, or may generate during the life time of the SSD. When the Bad Blocks is detected, it will be flagged, and not be used anymore. The SSD implement Bad Blocks management and replacement, Error Correct Code to avoid data error occurred. The functions will be enabled automatically to transfer data from Bad Blocks to spare blocks, and correct error bit. After the reserved block less than 40, the SSD will be locked, and cannot be written anymore.

3. Specifications

3.1 CE and FCC Compatibility

USB EDC Horizontal 2SE conforms to CE and FCC requirements.

3.2 RoHS Compliance

USB EDC Horizontal 2SE is fully compliant with RoHS directive.

3.3 Environmental Specifications

3.3.1 Temperature Ranges

Operating Temperature Range:

- Standard Grade: 0°C ~ +70°C
- Industrial Grade: -40°C to +85°C

Storage Temperature Range:

- Standard Grade: -55°C to +95°C

3.3.2 Humidity

Relative Humidity: 10-95%, non-condensing

3.3.3 Shock and Vibration

Reliability	Test Conditions	Reference Standards
Vibration	7 Hz to 2K Hz, 20G, 3 axes	IEC 68-2-6
Mechanical Shock	Duration: 0.5ms, 1500G, 3 axes	IEC 68-2-27

Table 1: Shock/Vibration Testing for USB EDC Horizontal 2SE

3.3.4 Mean Time between Failures (MTBF)

Table 2 summarizes the MTBF prediction results for various USB EDC Horizontal 2SE configurations. The analysis was performed using a RAM Commander™ failure rate prediction.

- Failure Rate: The total number of failures within an item population, divided by the total number of life units expended by that population, during a particular measurement interval under stated condition.

- Mean Time between Failures (MTBF): A basic measure of reliability for repairable items: The mean number of life units during which all parts of the item perform within their specified limits, during a particular measurement interval under stated conditions.

Product	Condition	MTBF (Hours)
USB EDC Horizontal 2SE	Telcordia SR-332 GB, 25°C	>3 ,000,000

Table 2: USB EDC Horizontal 2SE MTBF

3.3.5 Terabyte Written (TBW)

Parameter	Value
TBW(Sequential Write)	
512MB	27
01GB	54
02GB	108
04GB	216
08GB	432
16GB	864
32GB	1728

Table 3: USB EDC Horizontal 2SE TBW

3.4 Pin Assignment

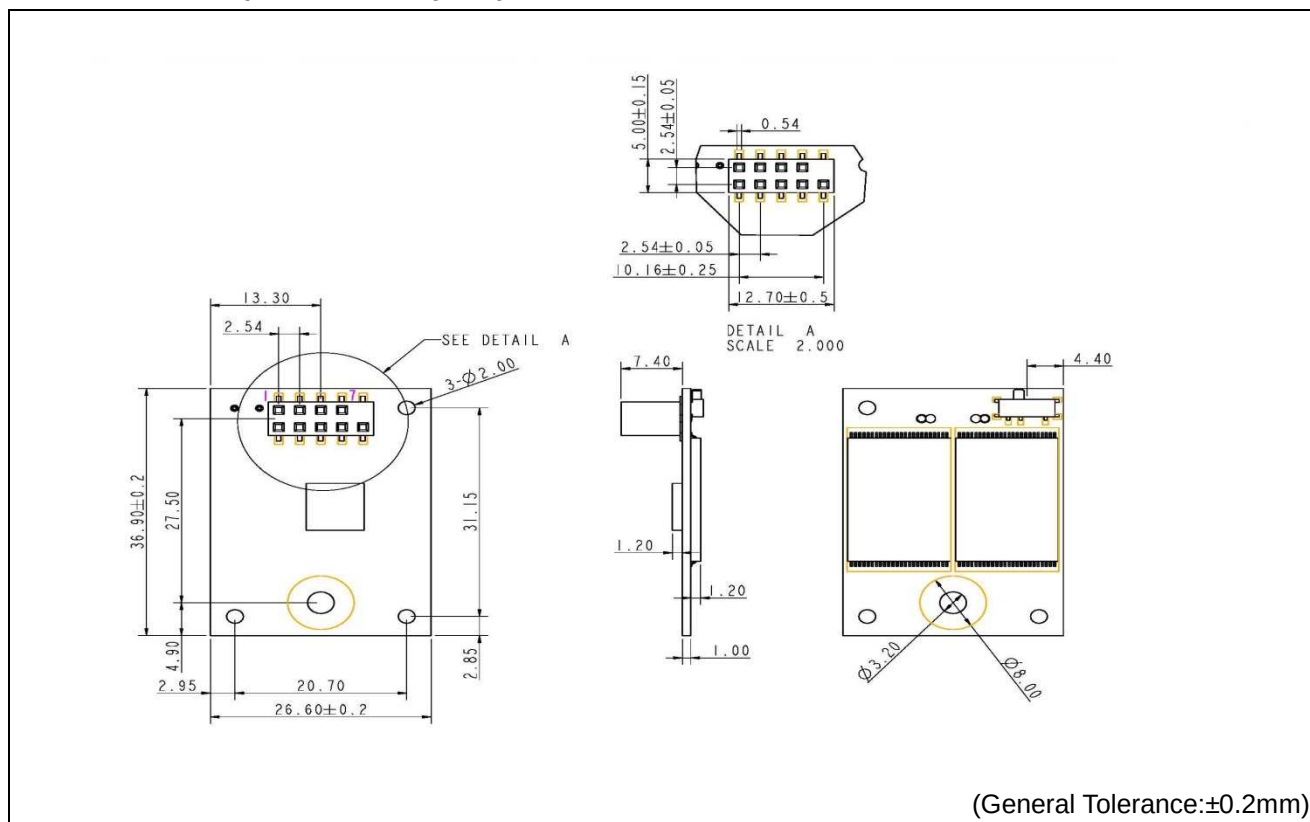
USB EDC Horizontal 2SE is designed within USB2.0 Interface. Particularly, its built-in power pin enables the device more compactable. Table 3 demonstrates USB EDC Horizontal 2SE pin assignments.

Horizontal Type			
Pin No.	Signal	Pin No.	Signal
1	+5VDC	2	NC
3	USB Data(-)	4	NC
5	USB Data(+)	6	NC
7	GND	8	NC
9	NC	10	NC

Table 4: USB EDC Horizontal 2SE Pin Assignment

3.5 Mechanical Dimensions

Pin Pitch: 2.54mm (Switch is for option)



Pin Pitch: 2.00mm (Switch is for option)

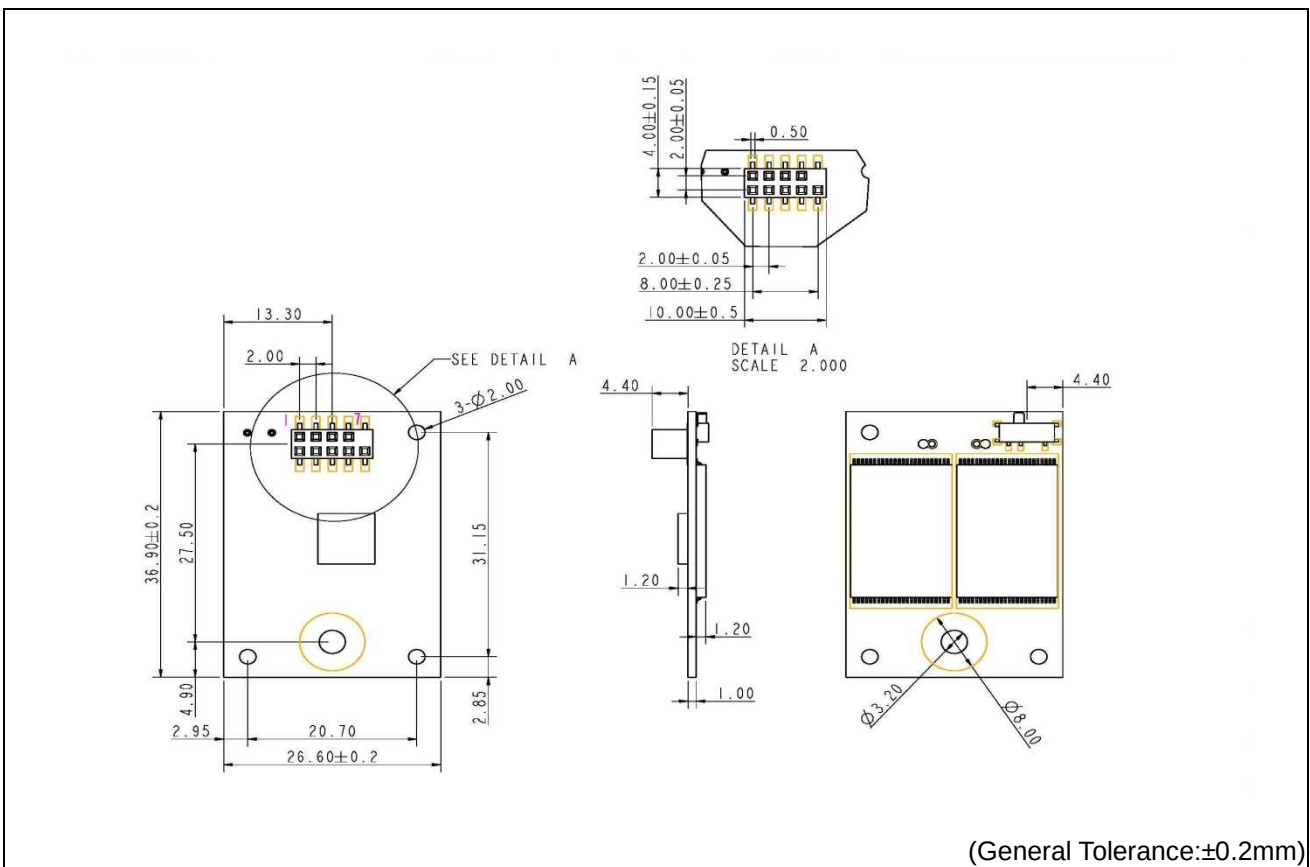


Figure 3: USB EDC Horizontal 2SE mechanical dimensions

3.6 Weight

5g±2

3.7 Performance

Product name		512MB	1GB	2GB	4GB	8GB	16GB	32GB
USB EDC Horizontal 2SE (Max.)	Sequential Read	24 MB/S	24 MB/S	24 MB/S	26 MB/S	26 MB/S	28 MB/S	28 MB/S
	Sequential Write	18 MB/S	20 MB/S	20 MB/S	24 MB/S	24 MB/S	24 MB/S	24 MB/S

3.8 NAND Flash Memory

USB EDC Horizontal 2SE uses Single Level Cell (SLC) NAND flash memory, which is non-volatility and high reliability and high speed memory storage.

4. Electrical Specifications

4.1 Power Requirement

Item	Symbol	Rating	Unit
Input voltage	V _{IN}	+5 DC +- 5%	V

Table 5: USB EDC Horizontal 2SE Power Requirement

4.2 Power Consumption

Mode	Power Consumption
Read	170 mA (max.)
Write	160 mA (max.)
Idle	110 mA (max.)
The power consumption is based on 32GB model.	

Table 6: USB EDC Horizontal 2SE Power Consumption

4.3 Device Parameters

USB EDC device parameters listed in Table 7.

Capacity	LBA	User capacity (MB)
512MB	982016	479
1GB	2014208	983
2GB	4028416	1967
4GB	8105984	3958
8GB	16211968	7916
16GB	32481280	15860
32GB	64970752	31724

Table 7: USB EDC Horizontal 2SE Device parameters

5. Part Number Rule

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20
	D	E	U	H	1	-	3	2	G	I	7	2	A	C	1	S	B			
Description	Disk	Form Factor				-	Capacity			Category			Flash mode	Operation Temp.	PCB Version	Channel	Flash		Customized Code	
Definition																				
Code 1 st (Disk)										Code 13 th (Flash mode)										
D: Disk										A: Async Flash										
Code 2 nd ~ 5 th (Form Factor)										Code 14 th (Operation Temperature)										
EUH1: USB EDC(Pin pitch 2.54mm) EUH2: USB EDC(Pin pitch 2.00mm)										C: Standard Grade (0℃ ~ +70℃)										
Code 7 th ~9 th (Capacity)										W: Industrial Grade (-40℃ ~ +85℃)										
512: 512MB 01G: 1GB										Code 15 th (PCB Version)										
02G: 2GB 04G: 4GB										1: First Version										
08G: 8GB 16G: 16GB										Code 16 th (Channel)										
32G: 32GB										S: Single										
Code 10 th ~12 th (Category)										Code 17 th (Flash)										
I72: USB 2.0 Series										B: Toshiba SLC										

RoHS

innodisk

宜鼎國際股份有限公司 Innodisk Corporation

Page 1/1

Tel: (02) 7703-3000 Fax: (02) 7703-3555 Internet: <http://www.innodisk.com/>

RoHS 自我宣告書 (RoHS Declaration of Conformity)

Manufacturer Product: All Innodisk EM Flash and Dram products

- 一、宜鼎國際股份有限公司（以下稱本公司）特此保證售予貴公司之所有產品，皆符合歐盟 2011/65/EU 關於 RoHS 之規範要求。

Innodisk Corporation declares that all products sold to the company, are complied with European Union RoHS Directive (2011/65/EU) requirement.

- 二、本公司同意因本保證書或與本保證書相關事宜有所爭議時，雙方宜友好協商，達成協議。

Innodisk Corporation agrees that both parties shall settle any dispute arising from or in connection with this Declaration of Conformity by friendly negotiations.

Name of hazardous substance	Limited of RoHS ppm (mg/kg)
鉛 (Pb)	< 1000 ppm
汞 (Hg)	< 1000 ppm
鎘 (Cd)	< 100 ppm
六價鉻 (Cr 6+)	< 1000 ppm
多溴聯苯 (PBBs)	< 1000 ppm
多溴二苯醚 (PBDEs)	< 1000 ppm

立 保 證 書 人 (Guarantor)

Company name 公司名稱： Innodisk Corporation 宜鼎國際股份有限公司

Company Representative 公司代表人： Randy Chien 簡川勝

Company Representative Title 公司代表人職稱： Chairman 董事長

Date 日期： 2016 / 08 / 04



REACH Declaration of Conformity

Manufacturer Product: All Innodisk EM Flash and Dram products

1. 宜鼎國際股份有限公司（以下稱本公司）特此保證此售予貴公司之產品，皆符合歐盟化學品法案(Registration, Evaluation and Authorization of Chemicals: (EC) No 1907/2006 REACH) 以及附錄 XIV 中的限用物質之規定 (<http://www.echa.europa.eu/de/candidate-list-table> last updated: 12/01/2017, SVHC's 173)。

所提供之產品包含：(1) 產品或產品所使用到的所有原物料；(2) 包裝材料；(3) 設計、生產及重工過程中所使用到的所有原物料。

We Innodisk Corporation hereby declare that our products are in compliance with the requirements according to the (EC) No 1907/2006 REACH Regulation and restricted substances in Annex XIV (<http://www.echa.europa.eu/de/candidate-list-table> last updated: 12/01/2017, SVHC's 173)。

Products include: 1) Product and raw material used by the product; 2) Packaging material; 3) Raw material used in the process of design, production and rework.

2. 本公司同意因本保證書或與本保證書相關事宜有所爭議時，雙方宜友好協商，達成協議。
InnoDisk Corporation agrees that both parties shall settle any dispute arising from or in connection with this Declaration of Conformity by friendly negotiations.

立 保 證 書 人 (Guarantor)

Company name 公司名稱：InnoDisk Corporation 宜鼎國際股份有限公司

Company Representative 公司代表人：Randy Chien 簡川勝

Company Representative Title 公司代表人職稱：Chairman 董事長

Date 日期：2017 / 02 / 08



Verification of Compliance

Product Name : USB EDC Horizontal 2ME/2SE
 Model Number : DEUH1(2)-XXXI72 # % ※ & *
 XXX : 512MB~64GB
 # : Flash Mode
 % : Temperature (C : Commercial Temp W : Industrial Temp
 E: Extended Temp)
 ※ : PCB Version (A, B, C.... or 1, 2, 3...)
 & : Channel (S : Single, D : Dual)
 * : Flash Vender (T : Micron SLC, S : Samsung SLC, N : Micron MLC,
 B : Toshiba SLC, C: Toshiba MLC)
 Applicant : InnoDisk Corporation
 Address : 9F, No.100, Sec. 1, Xintai 5th Rd., Xizhi Dist., New Taipei City 221,
 Taiwan
 Report Number : S1022-U070-1302-273
 Issue Date : May 6, 2013
 Applicable Standards : EN 55022:2010 Class B ITE
 AS/NZS CISPR22:2009 Class B ITE
 EN 55024:2010
 EN 61000-4-2:2009
 EN 61000-4-3:2006+A1:2008+A2:2010
 EN 61000-4-4:2004+A1:2010

Based on the EMC Directive 2004/108/EC and the specifications of the customer, one sample of the designated product has been tested in our laboratory and found to be in compliance with the EMC standards cited above.



TAF 0905
 FCC CAB Code TW1053
 NVLAP Lab Code 200575-0
 IC Code 4699A
 VCCI Accep. No. R-1527, C-1609, T-1441, G-10,
 C-4400, T-1334, G-614



Central Research Technology Co.
 EMC Test Laboratory
 11, Lane 41, Fushuen St., Jungshan Chiu,
 Taipei, Taiwan, 104, R.O.C.
 Tel : 886-2-25984568
 Fax: 886-2-25984546

Tsun-Yu Shih

(Tsun-Yu Shih/ General Manager)

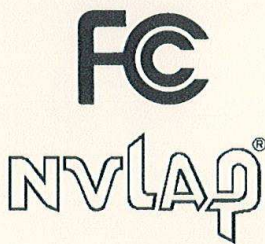
Date: May 6, 2013

Verification of Compliance

Product Name : USB EDC Horizontal 2ME/2SE
 Model Number : DEUH1(2)-XXXI72 # % ※ & *
 XXX : 512MB~64GB
 # : Flash Mode
 % : Temperature (C : Commercial Temp W : Industrial Temp
 E: Extended Temp)
 ※ : PCB Version (A, B, C.... or 1, 2, 3...)
 & : Channel (S : Single, D : Dual)
 * : Flash Vender (T : Micron SLC, S : Samsung SLC, N : Micron MLC,
 B : Toshiba SLC, C: Toshiba MLC)
 Applicant : InnoDisk Corporation
 Address : 9F, No.100, Sec. 1, Xintai 5th Rd., Xizhi Dist., New Taipei City 221,
 Taiwan
 Report Number : F-U070-1302-273
 Issue Date : May 6, 2013

Applicable Standards : FCC Part 15, Subpart B Class B ITE
 ANSI C63.4:2009
 Industry Canada ICES-003 Issue 5
 CSA-IEC CISPR22-10 Class B ITE

One sample of the designated product has been tested in our laboratory and found to be in compliance with the FCC rules cited above.



NVLAP LAB CODE 200575-0

TAF 0905

FCC CAB Code TW1053

IC Code 4699A

VCCI Accep. No. R-1527, C-1609, T-1441, G-10,
 C-4400, T-1334, G-614



Central Research Technology Co.
 EMC Test Laboratory
 11, Lane 41, Fushuen St., Jungshan Chiu,
 Taipei, Taiwan, 104, R.O.C.
 Tel : 886-2-25984568
 Fax: 886-2-25984546

J. Y. Shih

(Tsun-Yu Shih/ General Manager)

Date: May 6, 2013